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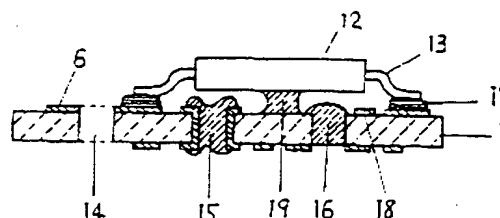
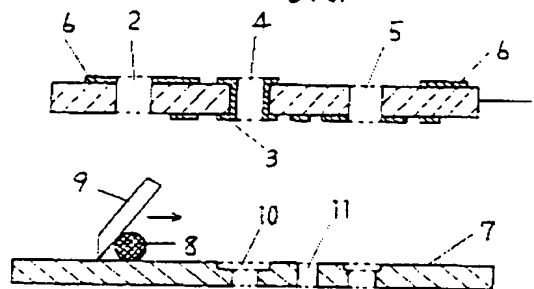
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APPLICANT : MATSUSHITA ELECTRIC IND CO LTD;

INVENTOR : TSUNASHIMA EIICHI;

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TITLE : MOUNTING OF COMPONENT ON
 PRINTED WIRING BOARD



ABSTRACT : PURPOSE: To fully prevent solder and flux from flowing out of holes above a surface mounting component and attaching to the underside of a printed wiring board by a method wherein a mask which is able to change an ink supply rate by stages is used.

CONSTITUTION: When a resin paste 8 is applied onto a printed wiring board 1 by the use of a squeegee 9 through a mask 7 which is provided with a stepped hole 10 and a non-stepped hole 11 corresponding to various kinds of holes such as through-holes 2 and 5, a through-hole plated hole 4, and other holes located in the component mounting region of the printed wiring board 1 and able to vary the ink supply rate in stages, the holes 5 and 4 different from each other in type are reliably and easily filled with the paste 8 through a single process. Solder and flux are fully prevented from flowing out of hole above a surface mounting component and attaching to the underside of the printed wiring board 1 at the time when leads 13 of a component 12 whose intermediate part is fixed to the board 1 with resin are soldered with conductive pastes 17 through a reflow soldering method.

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